

IN THE SPECIFICATION

Please amend the paragraph bridging pages 7-8 to read as follows:

Die pads 42 on one side for flip-chip die attachment as well as an outer row or rows of solder ball pads 43 on the other side, are each connected by a conductive line 44 of one of circuits 15 or 15C (lines 44 on both sides of the substrate are shown in Fig. 28 for purposes of illustration.) Figure 29 illustrates a ground plane 45 with current passing through the sintered conductive paste material in the vias when moving between a plane 45 and a pad 42 or 43. Solder ball pads 43 may be given an OSP, silver or tin finish, and die pad pads 42 may have a copper/OSP or solder finish. Connections for lines 44 are similar, except that a single via including three stacked "cones" of conductive filler material penetrates the entire thickness of the assembly, either at the location of pad 42 or 43.